



## Data and signal line chokes

Common-mode chokes, ring core  
4.7 ... 10 mH, 200 ... 300 mA, +40 °C

**Series/Type:**            **B82720H14**

**Date:**                    December 2023

**Rated voltage 42 V AC / 80 V DC**  
**Rated current 200 ... 300 mA / +40 °C**  
**Nominal inductance 4.7 ... 10 mH**

### Construction

- Current-compensated ring core quad choke
- Ferrite core
- Polycarbonate case (UL 94 V-0)
- Polyurethane potting (UL 94 V-0)

### Features

- Suitable for automatic insertion
- Suitable for wave soldering
- RoHS-compatible

### Applications

- Telecom switching systems
- Terminal systems
- Measuring and control lines

### Terminals

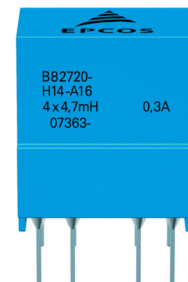
- Base material CuNi18Zn20
- Layer composition Ni, Sn
- Hot-dipped

### Marking

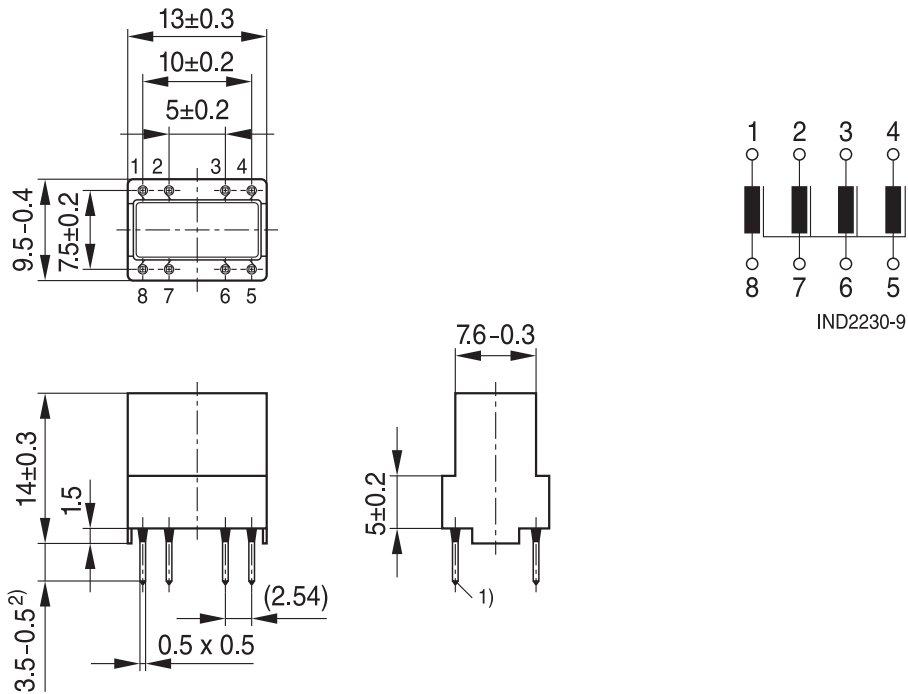
- Product brand (EPCOS), ordering code, rated inductance, rated current, date of manufacture (YYWWD)

### Delivery mode

- Cardboard box
- Delivery in tube magazine is available on request for B82720H\*



Dimensional drawing and pin configuration



1) Tin tips permissible

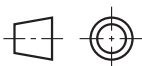
2) Dimension does not include tin tip

IND2199-E-E

Tolerances to ISO 2768-c / ISO 8015.

Size ISO 14405 (E)

All dimensions in mm



IND2200-F-E

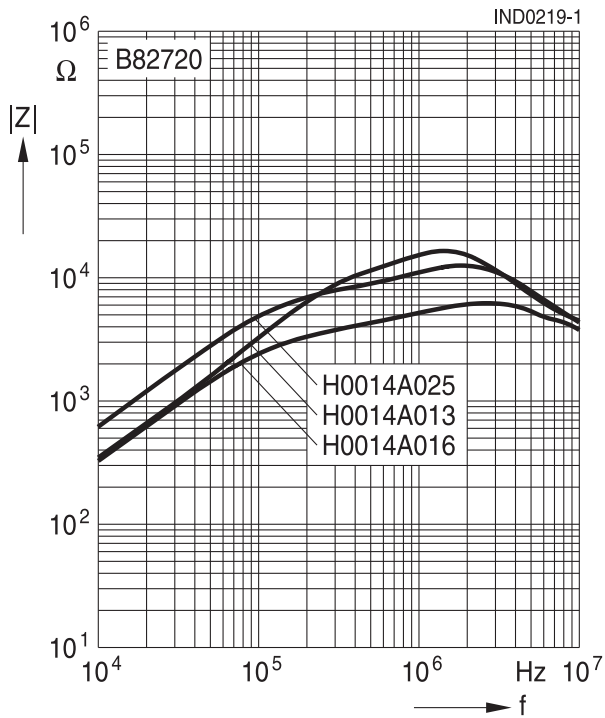
**Technical data and measuring conditions**

Rated voltage $V_R$	42 V AC (50/60 Hz) / 80 V DC
Rated temperature $T_R$	+40 °C
Rated current $I_R$	Referred to 50 Hz and rated temperature
Nominal inductance $L_R$	Measured with Agilent 4284A at 10 kHz, 0.1 mA, +20 °C Inductance is specified per winding.
Inductance tolerance	-30%/+50% at +20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with $I_R$ , +20 °C
Stray inductance $L_{\text{stray,typ}}$	Measured with Agilent 4284A at 10 kHz, 5 mA, +20 °C, typical values
DC resistance $R_{\text{typ}}$	Measured at +20 °C, typical values
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: +(245 ±5) °C, (3 ±0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat (wave soldering)	+(260 ±5) °C, (10 ±1) s (to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions (packaged)	-25 °C ... +40 °C, ≤ 75% RH
Weight	Approx. 2.3 g

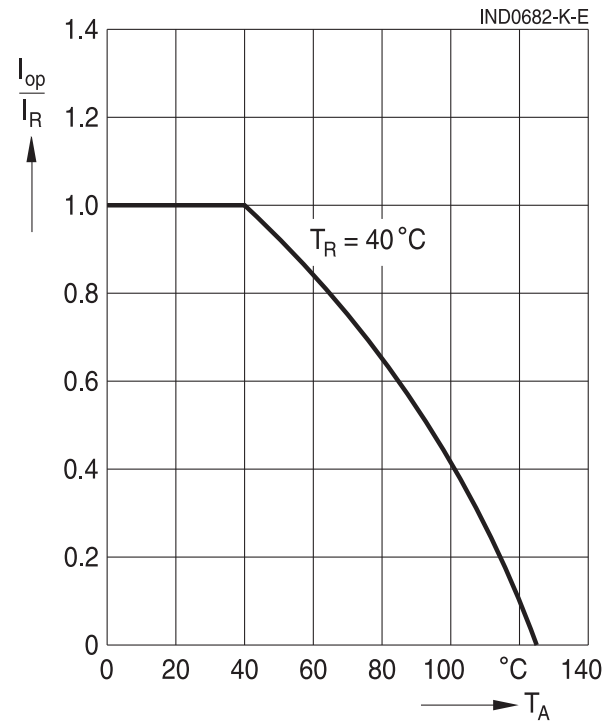
**Characteristics and ordering codes**

$L_N$ mH	$L_{\text{stray,typ}}$ nH	$I_R$ mA	$R_{\text{typ}}$ mΩ	$V_{\text{test}}$ V DC, 2 s	Ordering code
4.7	350	300	900	750	B82720H0014A016
5.0	400	300	550	750	B82720H0014A013
10	450	200	1300	750	B82720H0014A025

**Impedance  $|Z|$  versus frequency  $f$**   
 measured with windings in parallel at +20 °C,  
 typical values



**Current derating  $I_{op}/I_R$**   
 versus ambient temperature



### Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition), online catalogs and in the data sheets.
  - Particular attention should be paid to the derating curves, if given. Derating applies in the case the ambient temperature in application exceeds the rated temperature of the component.
  - Ensure the operation temperature of the component in application not to exceed the maximum specified value or the upper climatic category temperature.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. It is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
 

Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g., ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted, sealed, or varnished in customer applications:
  - Many potting, sealing, or varnishing materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting, sealing or varnishing materials used attack or destroy the wire insulation, plastics, or glue.
  - The effect of the potting, sealing, or varnishing materials may change the high-frequency behavior of the components.
- Magnetic core materials such as ferrites are sensitive to direct impact. This can cause the core material to flake or lead to breakage of the magnetic core material.
- Any type of tension or pressure on the product may result in damage and affect its functionality and reliability.
  - The products are only to be attached to fixings or mounting holes provided for this purpose in accordance with the data sheet.
  - If additional mechanical forces are applied to the component, e.g., application of gap pads, it is necessary to check whether they attack or destroy any part of the component.
  - It is not permitted for the product specified in the data sheet to assume a mechanical function in the final application.
- Inductance value can drop if external metallic or magnetic parts will be put close to the coil or into the air gap of the coil or core or magnetic material.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
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## Important notes

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